

LC-AD1Y2T3FEOGB

The detector includes a 5 pin APD plus AGC Pre-amplifier, supports 10Gbps long distance fiber communication application.

Features

- ◆ Differential output
- ◆ Coaxial package
- ◆ Single power supply voltage +3.3V
- ◆ InGaAs/InP avalanche photodiodes (APD) with transimpedance
- ◆ Laser welding, high reliability and long operation life
- ◆ Wavelength from 1260nm to 1620nm
- ◆ Operates from 9.95Gb/s to 11.3Gb/s NRZ rates
- ◆ High-sensitivity (-25dBm typical)
- ◆ RoHS compliant products available

Applications

- ◆ 10Gb ether net
- ◆ Fiber channel

Ordering information (Standard version ^{*Note1})

Part No	Wavelength (nm)	Bandwidth (GHz)	TIA supply voltage (V)	Pin type
LC-AD1Y2T3FEOGB	1260~1620	10	3.3	F

*Note1: For more ordering information, please refer the nomenclature and contact EPOTOLINK sales.

Absolute maximum ratings

Parameter	Symbol	Min	Max	Unit
Power supply voltage	VP	-0.5	4	V
Storage temperature	Tstg	-40	85	°C
Case temperature	Tc	-40	85	°C

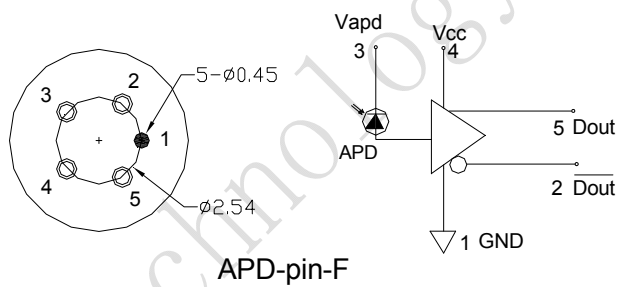
Electrical/optical characteristics

Parameter	Symbol	Min	Typ.	Max	Unit	Test conditions
Supply current	I _{cc}	44	58	72	mA	V _{cc} =3.3V
Supply voltage	V _{cc}	—	3.3	—	V	
APD breakdown voltage	V _{br}	25	—	36	V	APD Break-down Voltage in dark at I _d =10 μA
Dark current	I _d	—	—	50	nA	In dark, at V _{br} -3V, 25°C
Responsivity	R	0.8	—	—	A/W	λ=1550nm, P _{in} =10uW, M=1
Sensitivity	Sen	—	-25	—	dBm	λ=1550nm, PRBS=2 ²³ -1, BER=10 ⁻¹² , ER=10dB, Speed=10Gbps, M=10

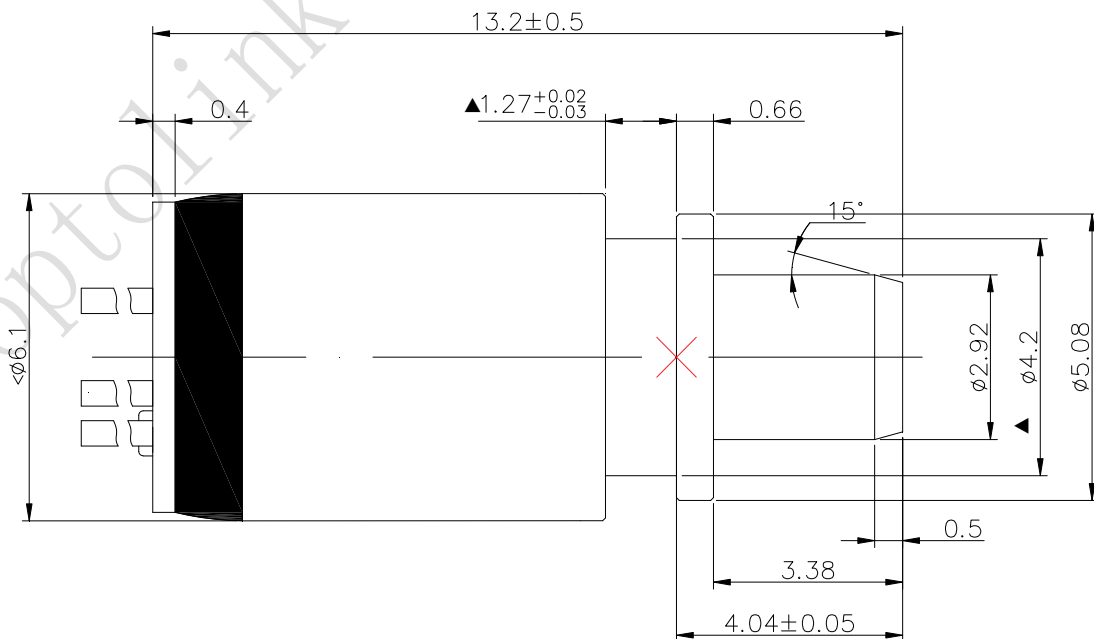
Note2: This data is test by stub ROSA

Pin assignment

TYPE: F



Package dimension ^{*Note3}



*Note3: Insulation is the TO-CAN and the metal pipe insulation.

Nomenclature

L C—A D

A B C D E F G H

Code	Parameter	Detailed description
A	Split sleeve Type	1=Structure 1
B	Insulation	Y= Insulation
C	Wavelength	2=1260~1620nm
D	Date rate	T=10Gb/s
E	TIA Voltage	3=3.3V
F	Pin Type	F=APD-pin-F
G	Rx Chip Type	EO=Eoptolink
H	TIA Type	GB=GN1058

Precaution

- (1) The modules should be handled in the same manner as ordinary semiconductor devices to prevent the electro-static damages. For safe keeping and carrying, the modules should be packaged with ESD proof material. To assemble the modules on PCB, the workbench, the soldering iron and the human body should be grounded.
- (2) Please pay special attention to the atmosphere condition because the dew on the module may cause some electrical damages.
- (3) Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed.

Obtaining document

You can visit our website:

<http://www.eoptolink.com>

Or contact Eoptolink Technology Inc., Ltd. listed at the end of the documentation to get the latest documentation.

Revision history

Verision	Initiated	Reviewed	Approved	Revision history	Release date
Va-1	Yinchun.zhao	James.liu	Vincent.yu	Released	2020.5.20
Va-2	Yinchun.zhao	James.liu	Vincent.yu	Data Update	2021.11.1

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